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PNP SILICON PLANAR EPITAXIAL TRANSISTOR

MPS4356

TO-92 Plastic Package



General Purpose Amplifier

ABSOLUTE MAXIMUM RATINGS

DESCRIPTION	SYMBOL	VALUE	UNITS
Collector Base Voltage	V_{CBO}	80	V
Collector Emitter Voltage	V_{CEO}	80	V
Emitter Base Voltage	V_{EBO}	5.0	V
Collector Current	I _C	800	mA
Power Dissipation @ T _a =25°C	P_{D}	625	mW
Derate Above 25°C		5.0	mW/ºC
Operating And Storage Junction Temperature Range	T_{j},T_{stg}	- 55 to +150	°C

THERMAL CHARACTERISTICS

Junction to Case	R _{th (j-c)}	83.3	°C/W
Junction to Ambient in free air	R _{th (j-a)}	200	°C/W

ELECTRICAL CHARACTERISTICS (T₂=25°C unless specified otherwise)

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
Collector Emitter Voltage	*V _{CEO}	$I_C=10$ mA, $I_B=0$	80			V
Collector Base Voltage	V_{CBO}	$I_{C}=10\mu A, I_{E}=0$	80			V
Emitter Base Voltage	V_{EBO}	$I_{E}=10\mu A, I_{C}=0$	5			V
Collector Cut Off Current	I _{CBO}	$V_{CB} = 50V, I_{E} = 0$			50	nA
		V_{CB} =50V, I_{E} =0, T_{a} =75°C			5.0	μΑ
Emitter Cut Off Current	I _{EBO}	$V_{EB}=4V$, $I_C=0$			100	nA
DC Current Gain	*h _{FE}	V_{CE} =10V, I_{C} =100 μ A	25			
		V_{CE} =10V, I_{C} =1mA	40			
		V_{CE} =10V, I_{C} =10mA	50		250	
		V_{CE} =10V, I_{C} =100mA	40			
		V_{CE} =10V, I_{C} =500mA	30			
Collector Emitter Saturation Voltage	*V _{CE (sat)}	$I_C=150$ mA, $I_B=15$ mA			0.15	V
		I_C =500mA, I_B =50mA			0.50	V
Base Emitter Saturation Voltage	*V _{BE (sat)}	$I_C=150$ mA, $I_B=15$ mA			0.90	V
		I _C =500mA, I _B =50mA			1.10	V

^{*}Pulse test pulse width<a>300ms, duty cycle <a>2%





ELECTRICAL CHARACTERISTICS (T_a=25°C unless specified otherwise)

DYNAMIC CHARACTERISTICS

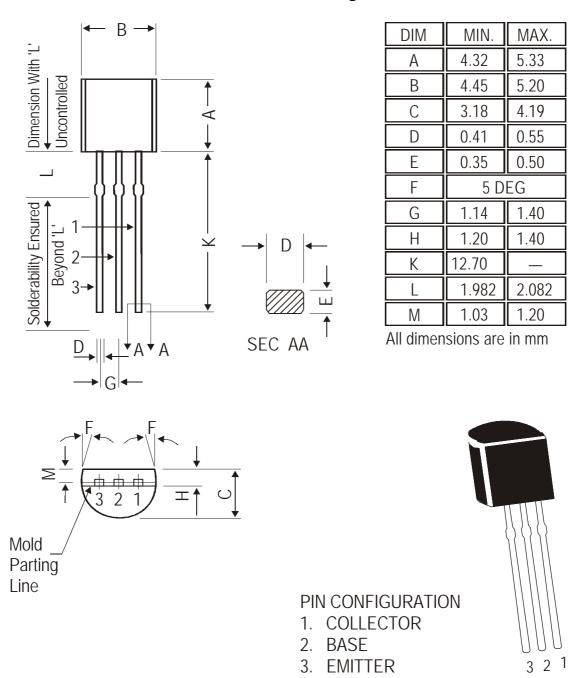
DESCRIPTION	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
Output Capacitance	C_{ob}	V_{CB} =20V, I_{E} =0,f=1MHz			30	pF
Input Capacitance	C_{ib}	V_{BE} =0.5V, f=1MHz			110	pF
Small Signal Current Gain	h _{fe}	I _C =0.5V, V _{CE} =10V, f=100MHz	1.0		5.0	
Noise Figure	NF	V_{CE} =10V, I_{C} =100mA, R_{S} =1K Ω , f =1KHz, B_{W} =1Hz			3.0	dB

SWITCHING CHARACTERISTICS

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
Turn On Time	t _{on}	V_{CC} =30V, I_{C} =500mA,			100	ns
Turn Off Time	t _{off}	$I_{B1}=I_{B2}=50mA$			400	ns

TO-92 Plastic Package

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The TO-92 Package, Tape and Ammo Pack Drawings are correct as on the date of issue/revision of this Data Sheet.

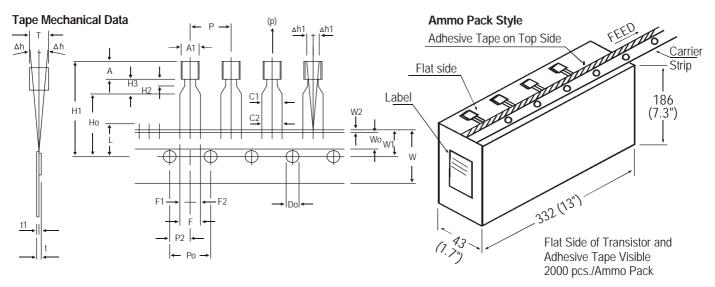
The currently valid dimensions and information, may please be confirmed from the TO-92 Drawing in the Packages and Packing Section of the Product Catalogue.

Packing Details

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
TO-92 Bulk	1K/polybag	200 gm/1K pcs	3" x 7.5" x 7.5"	5K	17" x 15" x 13.5"	80K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2K	17" x 15" x 13.5"	32K	12.5 kgs

TO-92 Plastic Package

TO-92 Tape and Ammo Pack



All dimensions are in mm

		SPECIFICATION				
ITEM	SYMBOL	MIN.	NOM.	MAX.	TOL.	
BODY WIDTH	A1	4.0		4.8		
BODY HEIGHT	А	4.8		5.2		
BODY THICKNESS	Т	3.9		4.2		
PITCH OF COMPONENT	Р		12.7		± 1.0	
*1FEED HOLE PITCH	Po		12.7		± 0.3	
*2 FEED HOLE CENTRE TO						
COMPONENT CENTRE	P2		6.35		$\pm~0.4$	
DISTANCE BETWEEN OUTER					+ 0.6	
LEADS	F		5.08		- 0.2	
*3 COMPONENT ALIGNMENT SIDE VIEW	∆h		0	1.0		
*4 COMPONENT ALIGNMENT FRONT VIEW	∆h1		0	1.3		
TAPE WIDTH	W		18		± 0.5	
HOLD-DOWN TAPE WIDTH	Wo		6		± 0.2	
HOLE POSITION	W1		9		+ 0.7	
					- 0.5	
HOLD-DOWN TAPE POSITION	W2		0.5		± 0.2	
LEAD WIRE CLINCH HEIGHT	Но		16		± 0.5	
COMPONENT HEIGHT	H1			23.25		
LENGTH OF SNIPPED LEADS	L			11.0		
FEED HOLE DIAMETER	Do		4		± 0.2	
*5 TOTAL TAPE THICKNESS	t			1.2		
LEAD - TO - LEAD DISTANCE	F1, F2		2.54		+ 0.4	
STAND OFF	H2	0.45		1.45	- 0.1	
CLINCH HEIGHT	H3	0		3.0		
LEAD PARALLELISM	C1 - C2			0.22		
PULL - OUT FORCE	(p)	6N				

NOTES

- 1. Maximum alignment deviation between leads will not to be greater than 0.2mm.
- Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.
- 3. Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.
- 4. There will be no more than three (3) consecutive missing components in a tape.
- 5. A tape trailer, having at least three feed holes are provided after the last component in a tape.
- 6. Splices should not interfere with the sprocket feed holes.

REMARKS

- *1 Cumulative pitch error 1.0 mm/20 pitch
- *2 To be measured at bottom of clinch
- *3 At top of body
- *4 At top of body
- *5 t1 0.3 0.6 mm

Notes MPS4356

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Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Discrete Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Discrete Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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CDIL is a registered Trademark of
Continental Device India Limited
C-120 Naraina Industrial Area, New Delhi 110 028, India.
Telephone + 91-11-2579 6150, 5141 1112 Fax + 91-11-2579 5290, 5141 1119
email@cdil.com www.cdilsemi.com